

# PHOTOCOUPLER PS2706-1

## AC INPUT RESPONSE DARLINGTON TRANSISTOR SOP MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

#### **DESCRIPTION**

The PS2706-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon darlington-connected phototransistor.

This is mounted in a plastic SOP (Small Out-line Package) for high density applications.

This package has shield effect to cut off ambient light.

### **FEATURES**

- · AC input response
- High current transfer ratio (CTR = 2 000 % TYP.)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- · Small and thin (SOP) package
- High-speed switching (t<sub>r</sub>, t<sub>f</sub> = 200 μs TYP.)
- Ordering number of taping product: PS2706-1F3, F4
- UL approved: File No. E72422 (S)
- · VDE0884 approved (Option)

### **APPLICATIONS**

- Hybrid IC
- Telephone, Exchange equipment
- FA/OA equipment
- Programmable logic controllers

### **ORDERING INFORMATION (Solder Contains Lead)**

Part Number	Package	Safety Standard Approval
PS2706-1	4-pin SOP	Standard specification products
		UL approved
PS2706-1-V	4-pin SOP	VDE0884 specification products (Option)

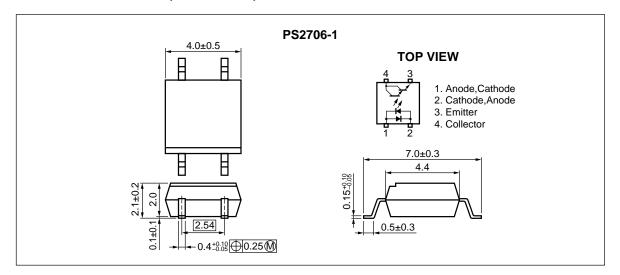
### **ORDERING INFORMATION (Pb-Free)**

Part Number	Package	Safety Standard Approval	
PS2706-1-A	4-pin SOP	Standard specification products	
		UL approved	
PS2706-1-V-A	4-pin SOP	VDE0884 specification products (Option)	

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

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### **★ PACKAGE DIMENSIONS (in millimeters)**



### ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current (DC)	lf	±50	mA
	Power Dissipation Derating	⊿P₀/°C	0.8	mW/°C
	Power Dissipation	Po	80	mW
	Peak Forward Current*1	IFP	±1	Α
Transistor	Collector to Emitter Voltage	Vceo	40	V
	Emitter to Collector Voltage	Veco	6	V
	Collector Current	lc	200	mA
	Power Dissipation Derating	⊿Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Vo	oltage*2	BV	3 750	Vr.m.s.
Operating A	Ambient Temperature	TA	-55 to +100	°C
Storage Te	mperature	T <sub>stg</sub>	-55 to +150	°C

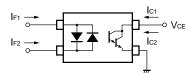
<sup>\*1</sup> PW = 100  $\mu$ s, Duty Cycle = 1 %

<sup>\*2</sup> AC voltage for 1 minute at  $T_A$  = 25 °C, RH = 60 % between input and output

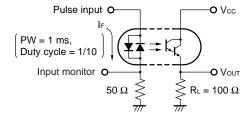
### **ELECTRICAL CHARACTERISTICS (TA = 25 °C)**

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	$I_F = \pm 5 \text{ mA}$		1.1	1.4	٧
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		60		pF
Transistor	Collector to Emitter Dark Current	Iceo	IF = 0 mA, VcE = 40 V			400	nA
Coupled	Current Transfer Ratio (Ic/I <sub>F</sub> )	CTR	IF = ±1 mA, VcE = 2 V	200	2 000		%
	CTR Ratio*1	CTR1/ CTR2	IF = ±1 mA, VcE = 2 V	0.3	1.0	3.0	
	Collector Saturation Voltage	VCE (sat)	IF = ±1 mA, Ic = 2 mA			1.0	V
	Isolation Resistance	R⊩o	Vi-o = 1 kVpc	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *2	tr	$Vcc = 5 \text{ V}, \ Ic = 2 \text{ mA}, \ R_L = 100 \ \Omega$		200		μS
	Fall Time *2	tr			200		

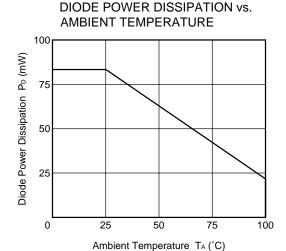
\*1 CTR1 = Ic1/IF1, CTR2 = Ic2/IF2



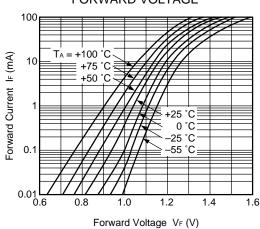
### \*2 Test circuit for switching time



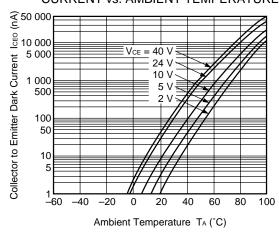
#### TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)



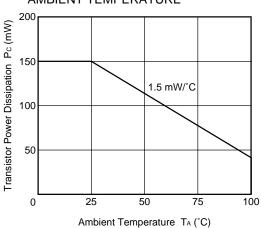
FORWARD CURRENT vs. FORWARD VOLTAGE



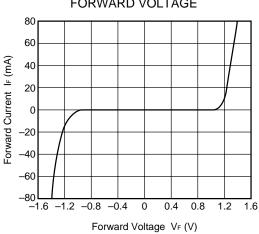
COLLECTOR TO EMITTER DARK **CURRENT vs. AMBIENT TEMPERATURE** 



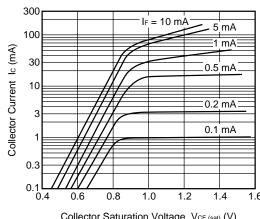
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD CURRENT vs. FORWARD VOLTAGE

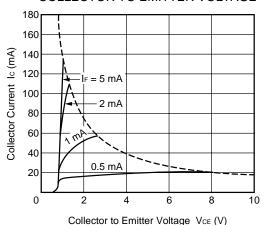


COLLECTOR CURRENT vs. **COLLECTOR SATURATION VOLTAGE** 

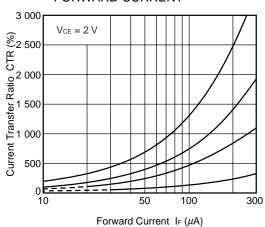


Collector Saturation Voltage VcE (sat) (V)

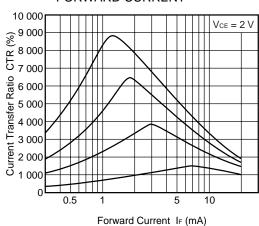
## COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



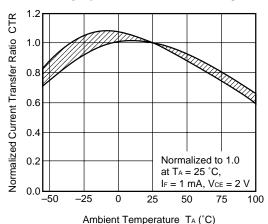
### CURRENT TRANSFER RATIO vs. FORWARD CURRENT



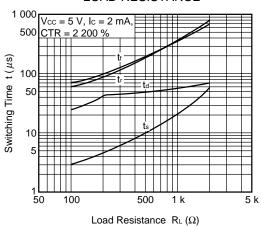
### CURRENT TRANSFER RATIO vs. FORWARD CURRENT



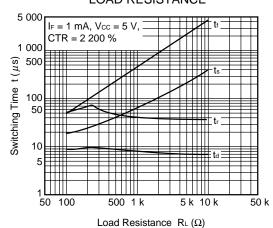
## NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE

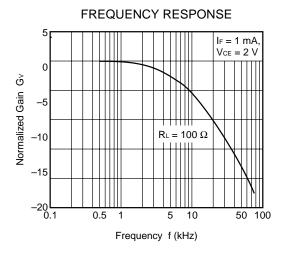


### SWITCHING TIME vs. LOAD RESISTANCE

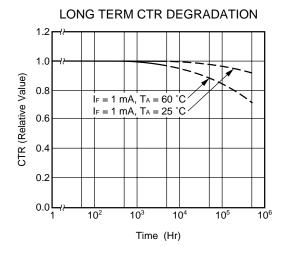


### SWITCHING TIME vs. LOAD RESISTANCE

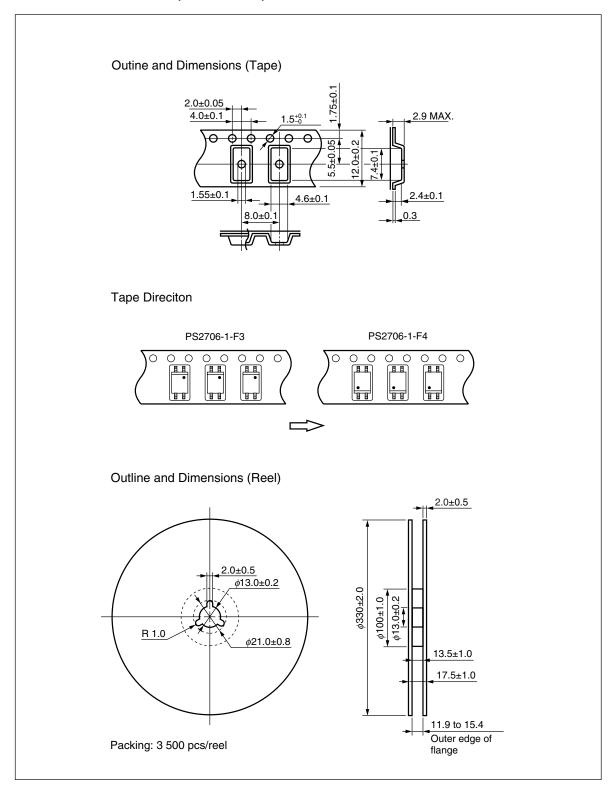




Remark The graphs indicate nominal characteristics.



### **★ TAPING SPECIFICATIONS (in millimeters)**



#### ★ NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

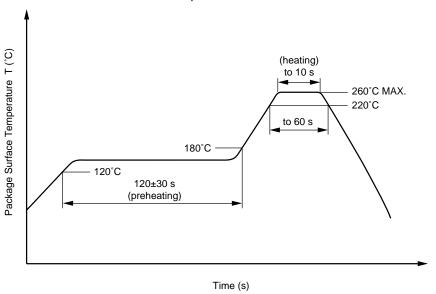
Time of peak reflow temperature
 Time of temperature higher than 220°C
 50 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

### Recommended Temperature Profile of Infrared Reflow



### (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

### (3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

### **★ USAGE CAUTIONS**

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

### SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (VDE0884)

	Parameter	Symbol	Speck	Unit
	Application classification (DIN VDE 0109) for rated line voltages ≤ 300 Vr.m.s. for rated line voltages ≤ 600 Vr.m.s.		IV III	
	Climatic test class (DIN IEC 68 Teil 1/09.80)		55/100/21	
	Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.2 \times U_{\text{IORM}},  P_d < 5 \; \text{pC}$	UIORM Upr	710 850	V <sub>peak</sub> V <sub>peak</sub>
*	Test voltage (partial discharge test, procedure b for all devices test) $U_{pr} = 1.6 \times U_{IORM}, \ P_d < 5 \ pC$	Upr	1 140	$V_{peak}$
	Highest permissible overvoltage	Utr	6 000	V <sub>peak</sub>
	Degree of pollution (DIN VDE 0109)		2	
	Clearance distance		> 5	mm
	Creepage distance		> 5	mm
	Comparative tracking index (DIN IEC 112/VDE 0303 part 1)	CTI	175	
	Material group (DIN VDE 0109)		III a	
	Storage temperature range	T <sub>stg</sub>	-55 to +150	°C
	Operating temperature range	TA	-55 to +100	°C
	Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at T}_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at T}_A \text{ MAX. at least } 100 \text{ °C}$	Ris MIN. Ris MIN.	10 <sup>12</sup> 10 <sup>11</sup>	Ω Ω
	Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
	Package temperature	Tsi	150	°C
	Current (input current IF, Psi = 0)	Isi	200	mA
	Power (output or total power dissipation)	Psi	300	mW
	Isolation resistance V <sub>IO</sub> = 500 V dc at T <sub>A</sub> = 175 °C (Tsi)	Ris MIN.	10 <sup>9</sup>	Ω

11



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration in CEL	on contained devices	
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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